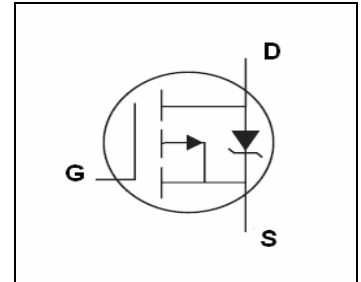


Features

- P-Channel
- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=-4.5V$
- Fast Switching
- Pb-free lead plating; RoHS compliant
- Green product

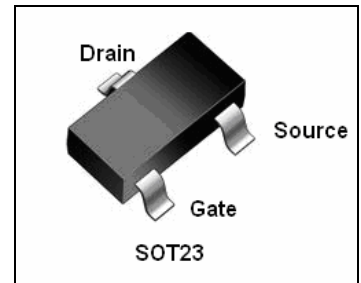


V_{DS}	-30	V
$R_{DS(on),typ. @ V_{GS}=-10V}$	85	m Ω
$R_{DS(on),typ. @ V_{GS}=-4.5V}$	100	m Ω
I_D	-2.8	A



Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS3403AC	A3V3	SOT23	3000/Reel	6000



Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	-30	V	
I_D	Continuous drain current @ $V_{GS}=10V$	$T_C=25^\circ\text{C}$	-2.8	A
		$T_A=70^\circ\text{C}$	-1.8	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ\text{C}$	-11.2	A
P_D	Maximum power dissipation	$T_C=25^\circ\text{C}$	1.3	W
V_{GS}	Gate-Source voltage	± 12	V	
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	$^\circ\text{C}$	
Thermal characteristics				
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	125	$^\circ\text{C/W}$	

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current (T _c =25°C)	V _{DS} =-30V, V _{GS} =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current (T _c =125°C)	V _{DS} =-30V, V _{GS} =0V	--	--	-100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-0.6	-1.0	-1.4	V
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-2.8A	--	85	110	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-4.5V, I _D =-2.0A	--	100	130	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-2.5V, I _D =-1.0A	--	145	180	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =-12V, V _{GS} =0V, f=1MHz	--	500	--	pF
C _{oss}	Output Capacitance		--	60	--	pF
C _{rss}	Reverse Transfer Capacitance		--	40	--	pF
Q _g	Total Gate Charge	V _{DS} =-15V, I _D =-2.0A, V _{GS} =-4.5V	--	4.5	--	nC
Q _{gs}	Gate-Source Charge		--	0.8	--	nC
Q _{gd}	Gate-Drain Charge		--	1.3	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =-15V, I _D =-2A, R _G =6Ω, V _{GS} =-4.5V, R _L =5Ω,	--	5	--	nS
t _r	Turn-on Rise Time		--	4	--	nS
t _{d(off)}	Turn-Off Delay Time		--	28	--	nS
t _f	Turn-Off Fall Time		--	8	--	nS
Source- Drain Diode Characteristics						
I _{SD}	Source-drain current(Body Diode)	T _c =25°C	--	--	-2.6 ^①	A
V _{SD}	Forward on voltage	T _j =25°C, I _{SD} =-2A, V _{GS} =0V	--	-0.85	-1.3	V

Notes: ① Pulse test ; Pulse width≤300μs, duty cycle≤2%.

Typical Characteristics

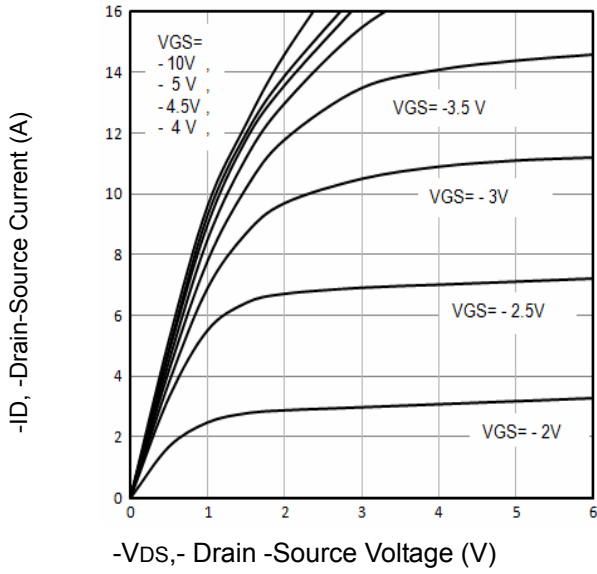


Fig1. Typical Output Characteristics

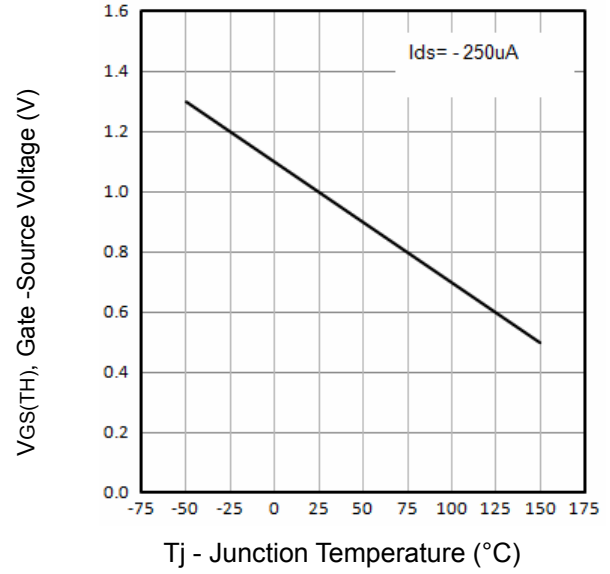


Fig2. Threshold Voltage Vs. Temperature

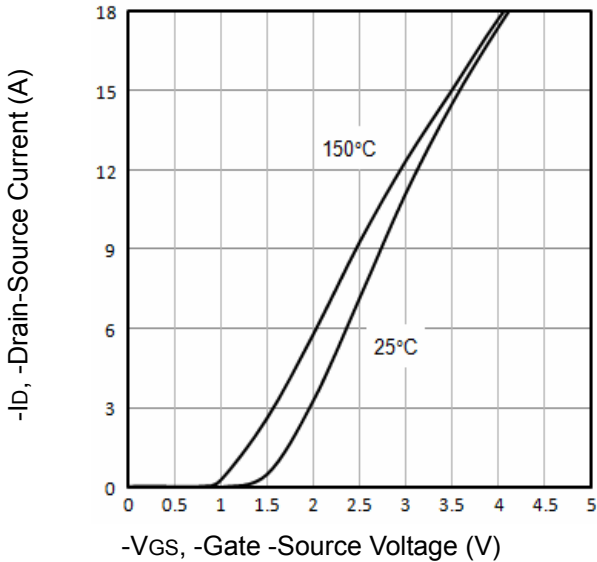


Fig3. Typical Transfer Characteristics

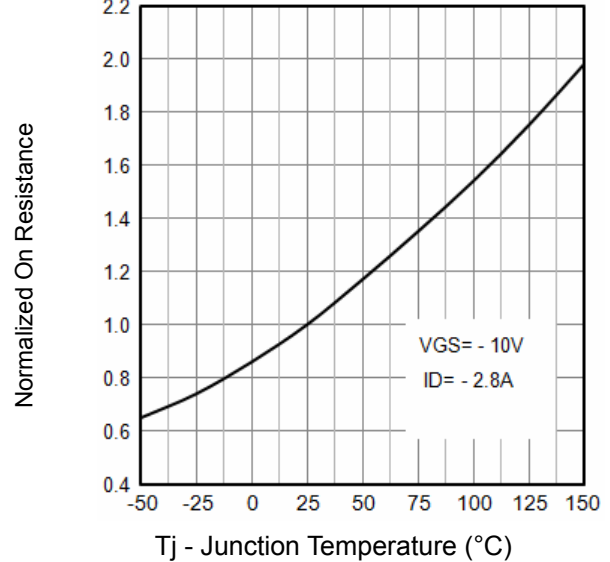


Fig4. Normalized On-Resistance Vs. Temperature

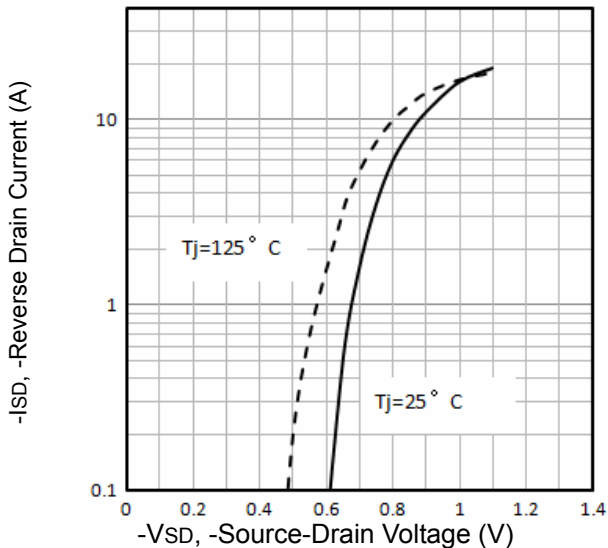


Fig5. Typical Source-Drain Diode Forward Voltage

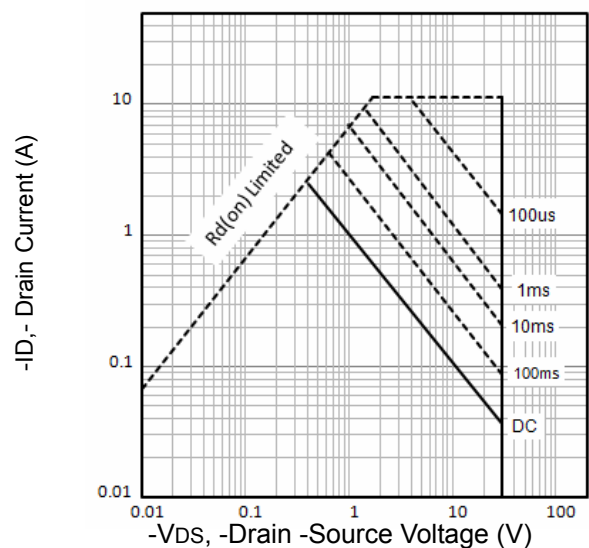


Fig6. Maximum Safe Operating Area

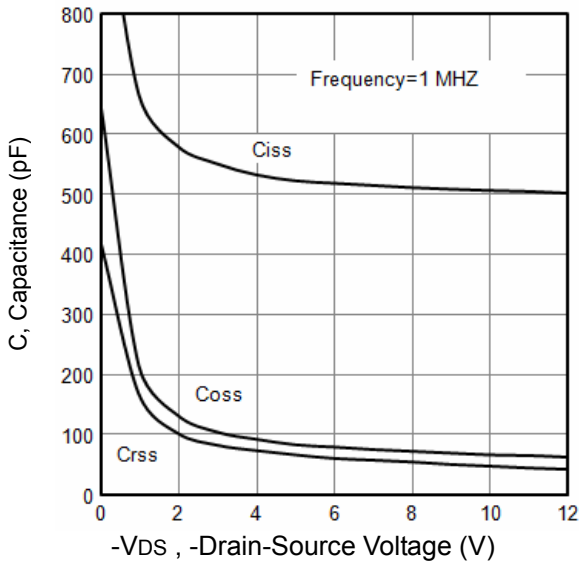


Fig7. Typical Capacitance Vs.Drain-Source Voltage

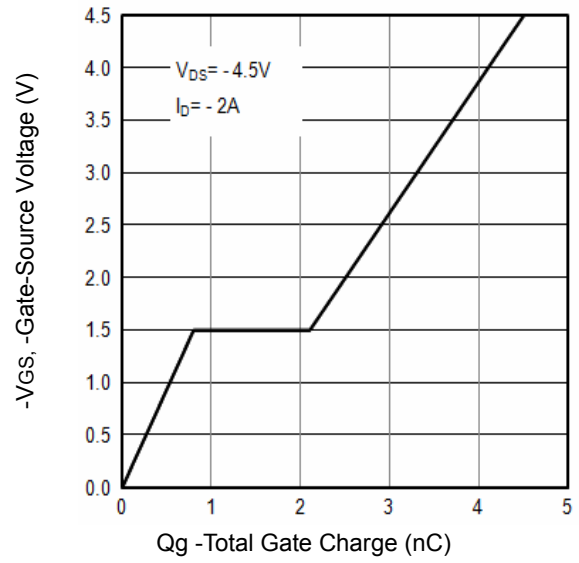


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

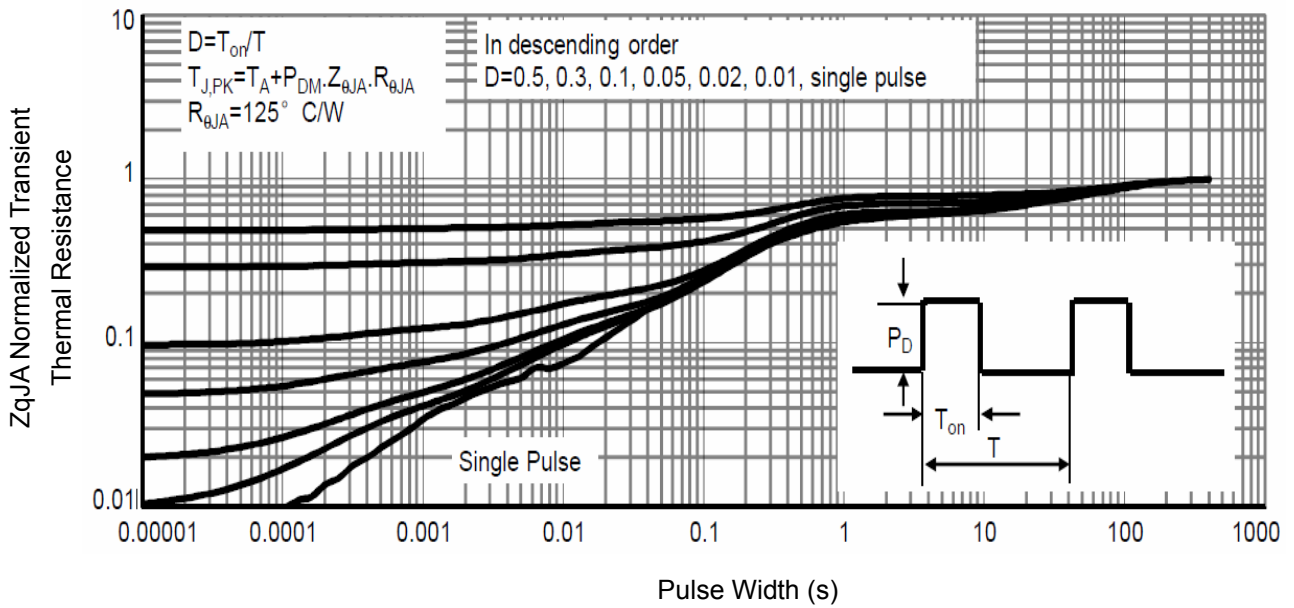


Figure 9: Normalized Maximum Transient Thermal

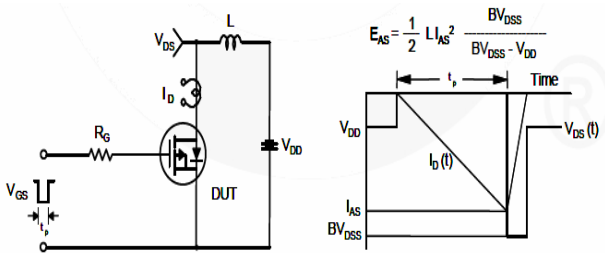


Fig10. Unclamped Inductive Test Circuit and Waveforms

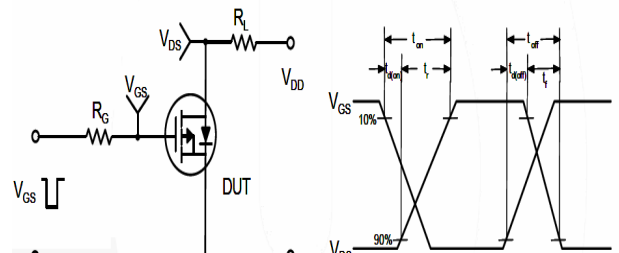
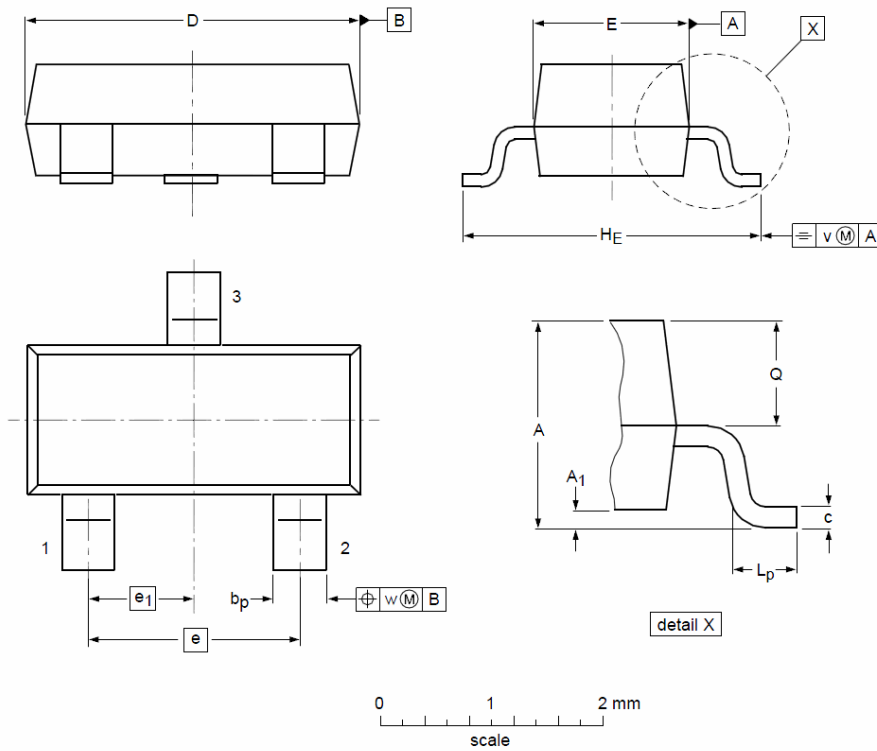


Fig11. Switching Time Test Circuit and waveforms

SOT23 Package Outline Data



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.03	1.10	A ₁	0.01	0.05	0.10
b _p	0.38	0.42	0.48	c	0.09	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e ₁	--	0.95	--
H _E	2.10	2.40	2.50	L _p	0.15	0.23	0.45
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

Customer Service

Sales and Service:

Sales@vgsemi.com

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: www.vgsemi.com